



2823

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

APPLICANT: RICHARD COOPER, ET AL.
TITLE: POLISHING PAD FOR USE IN CHEMICAL-...
SERIAL No.: 10/087,223
FILING DATE:
GROUP: ART UNIT
EXAMINER:

To: Hon. Commissioner of Patents & Trademarks
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

In advance of the first office action, please amend the above-identified application as follows.

IN THE CLAIMS:

Amend claim 1 as follows.

CLAIM 1(AMENDED). A process of making polishing for use in chemical mechanical polishing of substrates, each said polishing pad having a ground polishing surface and consisting of a porous fibrous matrix of paper-making fibers, fillers, and a binder for binding said fibrous matrix, said binder consisting of thermoset resin, said matrix and said binder forming a porous structure by which polishing slurry or polishing debris during chemical mechanical polishing of substrates are temporarily stored for subsequent rinsing away and for enhanced flow-distribution of the polishing slurry; said ground polishing surface consisting of a ground surface in order that